

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







HI2220T101R-10

UNCONTROLLED DOCUMENT

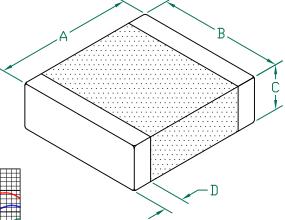
PHYSICAL DIMENSIONS:

A 5.59 [.220] ± 0.51 [.020]

B 5.08 [.200] ± 0.25 [.010]

C 1.80 [.071] ± 0.25 [.010]

D 0.76 [.030] ± 0.25 [.010]

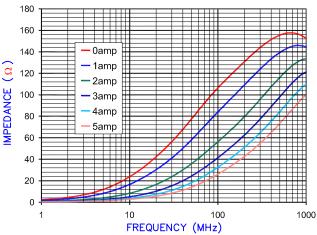


ELECTRICAL CHARACTERISTICS:									
Z @ 100MHz (Ω)		DCR $\left(\begin{array}{c}\Omega\end{array}\right)$	Rated Current						
Nominal	100								
Minimum	75								
Maximum	125	0.006	6000 mA						

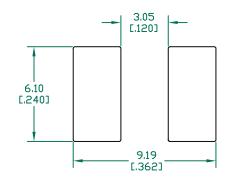
NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 13" REELS, 2,000 PCS/REEL.
- 2. TERMINATION FINISH IS 100% TIN.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. OPERATEING TEMPERATURE TEMP: -40°C~+125°C (INCLUDING SELF-HEATING)

Z vs. FREQUENCY IMPEDANCE UNDER DC BIAS

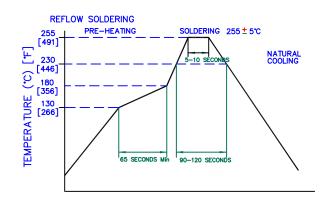


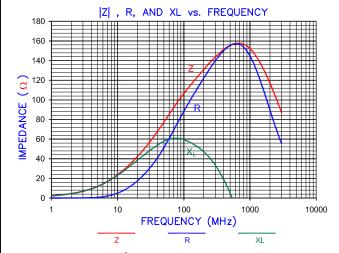
LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 [.030] to this dimension)

RECOMMENDED SOLDERING CONDITIONS





ROLS 2002/95/EC

	DIMENSIONS ARE IN mm [INCHES].			This print is the property of Laird				
				Technologies and is loaned in confidence subject to return upon		_	■ l	ı"
				request and with the understandin	a	-2		
				that no copies shall be made	" L	.C	ird	
				without the written consent of Lai	rd			
				Technologies All rights to design of invention are reserved.	or			
			_					
					_			
				PROJECT/PART NUMBER:	REV	PAR	T TYPE:	DRAWN BY:
С	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13		PROJECT/PART NUMBER: HI2220T101R—10	REV C	1	T TYPE: CO-FIRE	DRAWN BY: TMB
C B	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE UPDATE COMPANY LOGO ADD ROHS SYMBOL		QU	HI2220T101R-10	C	(
	UPDATE COMPANY LOGO ADD ROHS SYMBOL		QU JRK	HI2220T101R-10	C	1	O-FIRE	ТМВ

AGILENT E4991A RF Impedance/Material Analyzer HP 16092A Test Fixture. TEST REF. 3185